



## Material Content Data Sheet



<b>Sales Product Name</b>		BGA 713N7 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001067824						
<b>Package</b>		PG-TSNP-7-1		<b>Weight*</b>		3.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.114	2.97	2.97	29710	29710
leadframe	non noble metal	zinc	7440-66-6	0.004	0.11		1117	
	non noble metal	tin	7440-31-5	0.005	0.14		1396	
	non noble metal	chromium	7440-47-3	0.006	0.17		1675	
wire	non noble metal	copper	7440-50-8	2.136	55.42	55.84	554220	558408
	noble metal	gold	7440-57-5	0.042	1.10	1.10	10960	10960
	encapsulation	organic material	carbon black	1333-86-4	0.006	0.16		1641
	plastics	epoxy resin	-	0.183	4.76		47587	
		inorganic material	silicondioxide	60676-86-0	1.075	27.90	32.82	278957
leadfinish	non noble metal	tin	7440-31-5	0.111	2.89	2.89	28926	28926
plating	noble metal	silver	7440-22-4	0.104	2.69	2.69	26924	26924
glue	plastics	epoxy resin	-	0.013	0.34		3378	
		noble metal	silver	7440-22-4	0.052	1.35	1.69	13509
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com